

HBS-800S Series

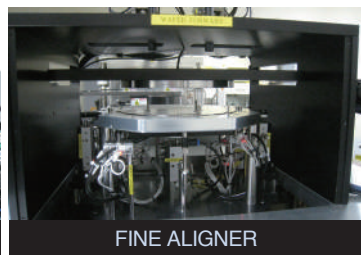
Semi Automation

* Fine Align available

* 8 inch, 4 inch and 2 inch process available



PROCESS MODULE



FINE ALIGNER



STACKER



TRASFER ROBOT

Application:

MicroLED, MiniLED, FBAR Filter, SAW Filter, CMOS Image Sensor, MEMS, Semiconductor, Acceleration Sensor, Vertical LED

FEATURE	WAFER SIZE	8 Inch (Option 12, 6 Inch)	
	WAFER	Si, Glass, and so on.	
	BONDING METHOD	Eutectic, adhesive, Thermo Compressive Standard	
	TYPE	Semi Automation	
MAIN MODULE	LOADING MODULE TRANSFER ROBOT MODULE PRE/FINE ALIGNER MODULE 1 PROCESS MODULE - CHAMBER, PRESS, HEATING, VACUUM PUMP		
DIMENSION (W x D x H)	WAFER BONDER	2700 x 3000 x 2000 mm	
	CONTROL BOX	1500 x 600 x 1500mm	
	VACUUM PUMP	477 x 925 x 839 mm	
LOADING MODULE	LOADING	MANUAL	
	UNLOADING	MANUAL	
TR (Transfer Robot)	WAFER SIZE	8 INCH (Option 12, 6 Inch)	
	ARM	WAFER LOADING JIG HANDLE	
	DRIVING	2 AXIS (X, T)	
COOLING STATION	WAFER SIZE	8 INCH (Option 12, 6 Inch)	
	MOVING	1 AXIS (Z)	
	COOLING	COOLING STATION (BY WATER)	
ALIGNER (PRE+FINE)	ALIGN STAGE	4 AXIS MOVING	
	CAMERA STAGE	3 AXIS MOVING	
	ACCURACY	<10um	
	TYPE	VISION (ALIGN KEY/TSA)	
PM (Process Module)	HEATING	TEMP	MAX. 400°C (OPTION 500°C)
		UNIFORMITY	RAMP : $\leq \pm 3\%$
			DWELL : $\leq \pm 1.5\%$
	PRESSURE	COOL : $\leq \pm 3\%$	
		FORCE	MAX 70kN
		UNIFORMITY	$\leq \text{SETTING PARAMETER} \pm 3\%$
	ACCURACY	$\leq \text{SETTING PARAMETER} \pm 1\%$	
CHAMBER	N2 + WATER COOLING		
VACUUM	MAX.30mmTorr		